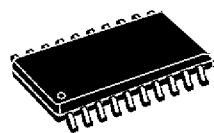


## ABS AND ISO/SDL INTERFACE

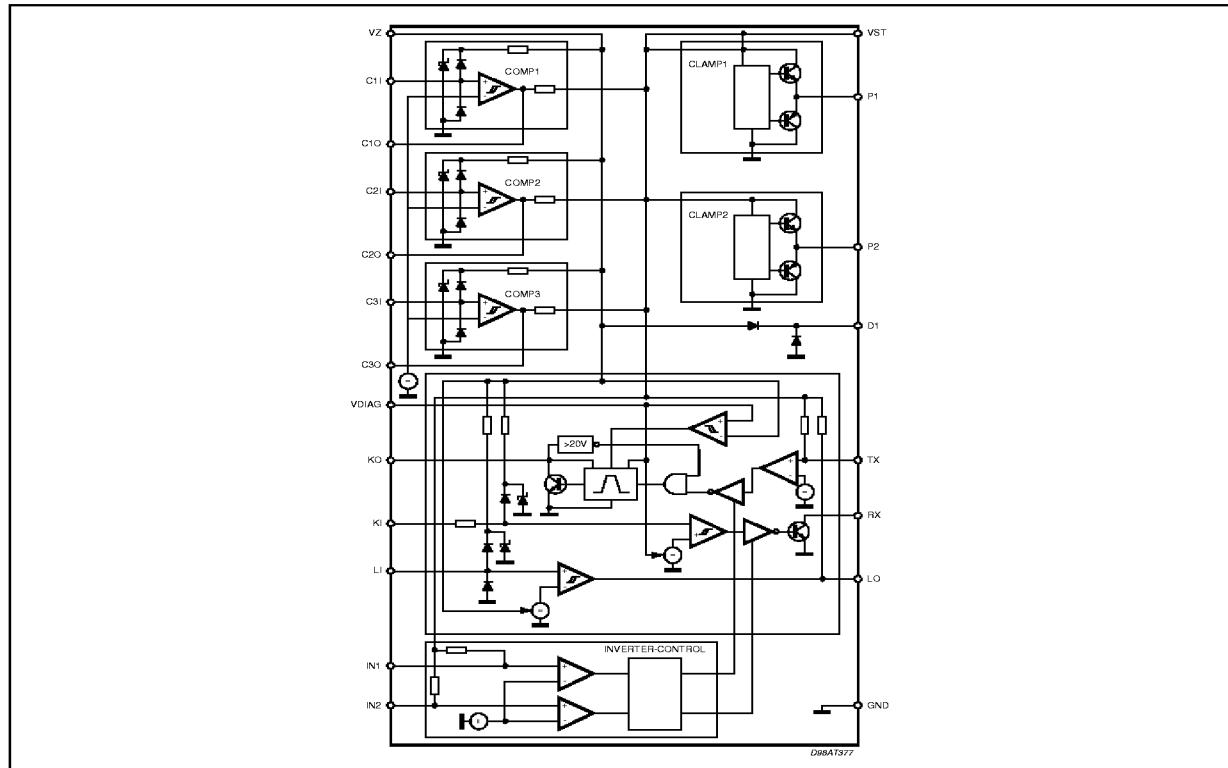
- THREE HYSTERESIS COMPARATORS WITH LOW INPUT CURRENTS, FIXED THRESHOLD VOLTAGES AND INTEGRATED OUTPUT PULL-UP RESISTORS.
- DIAGNOSTIC INTERFACE CIRCUIT WITH SUPPLY VOLTAGE DEPENDENT INPUT THRESHOLDS AND PROTECTED OPEN COLLECTOR OUTPUT
- EXTERNALLY PROGRAMMABLE ISO OR SDL FUNCTION FOR THE DIAGNOSTIC
- INVERTER CONTROL COMPARATORS WITH INTERNAL INPUT PULL-UP RESISTORS
- TWO PRECISION CLAMPING CIRCUITS
- ALL INPUTS AND OUTPUTS PROTECTED AGAINST ESD
- THERMAL SHUTDOWN FUNCTION FOR THE K DIAGNOSTIC OUTPUT


**SO20L**
**ORDERING NUMBER: L9864D**

### DESCRIPTION

The L9864 is a monolithic integrated circuit containing ABS and a programmable ISO/SDL interface function

### BLOCK DIAGRAM

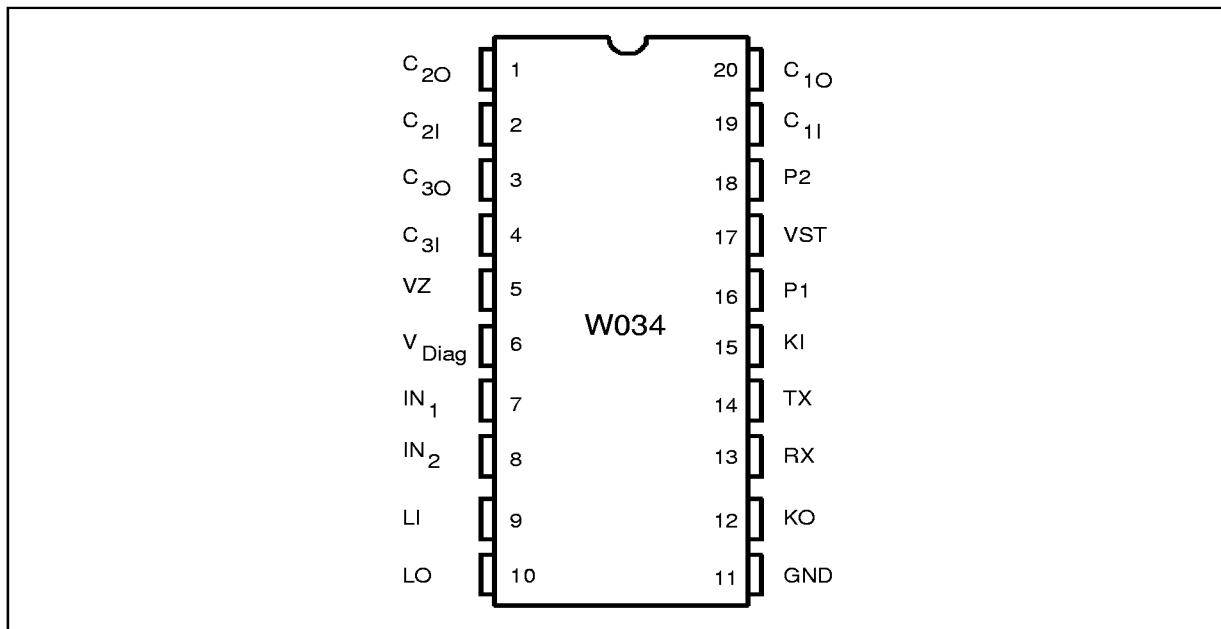


## ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Value	Unit
Vz, VDiag	Board Voltage	Continuous (DC)	0 to 20	V
		0 < tp ≤ 5min; Tj = -40 to 80°C	26.5	V
		tp ≤ 2s	-1.5	V
		0 < tp ≤ 200ms; f ≤ 0.06Hz; n ≤ 360 cycles	40	V
		0 < tp ≤ 50ms; f ≤ 1Hz; n ≤ 36000 cycles	40	V
dVz/dt, dVDiag/dt		Vz = 6 to 16V	10	V/μs
Vst	Stabilized Voltage		0 to 6	V
Tstg	Storage Temperature	continuous	-55 to 150	°C
Tj	Junction Temperature	continuous $\sum tp < 100h$ tp < 10ms	-55 to 150 170 180	°C °C °C
VKO, KI		positive transient (1)	50	V

Note 1: according to ISO TR 7637/1; the transient will be clamped with external circuitry.

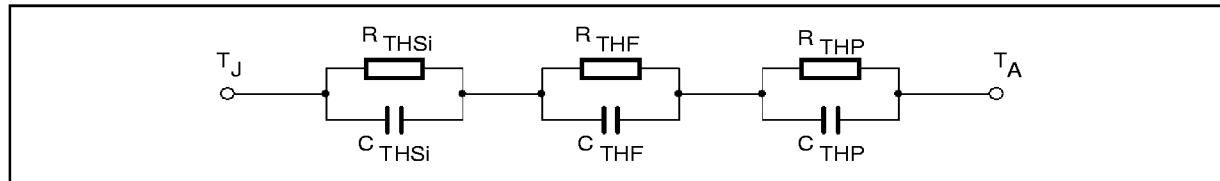
## PIN CONNECTION



## THERMAL DATA

Symbol	Parameter	Value	Unit
Rth j-amb	Thermal resistance Junction ambient SO20 (mounted on board)	max 80	K/W
TjTSD	Thermal Protection threshold Junction Temperature	150 to 180	°C

### Equivalent Circuit Diagram of the Thermal Impedance Junction to Ambient



Si = silicon and die attach

F = frame

P = remaining package mass

$$t_{HD} = \frac{1}{R_{TH} \cdot C_{TH}}$$

The typical values for SO20 package are:

$R_{THSi}$	= 1.5KW	$T_{THSi}$	= 2ms
$R_{THF}$	= 15KW	$T_{THF}$	= 20ms
$R_{THP}$	= 60KW	$T_{THP}$	= 50s

### ELECTRICAL CHARACTERISTICS (Operating Range)

The electrical characteristics are valid within the below defined operating range, unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$V_z$			6	12	16	V
$V_{Diag}$			4.75		16	V
$V_{ST}$			4.75	5	5.25	V
$T_{amb}$	Ambient Temperature	hybrid ass. chip	-40		125	°C
$t_B$	Useful Life Time	$V_z = V_{ST} = V_{Diag} = 0V$	15			years
$t_b$	Operating Life Time	$V_z = V_{ST} = V_{Diag}$ nominal values; $T_{amb} = 55^\circ\text{C}$	4500			hours

### Comparators (Comp 1, Comp 2, Comp 3)

$V_{C1L}$	Input Voltage Low State	$V_{C10} = (\text{LOW});  I_{C1}  \leq 10\text{mA}$			2	V
		$V_{C20} = (\text{LOW});  I_{C2}  \leq 10\text{mA}$			2	V
		$V_{C30} = (\text{LOW});  I_{C3}  \leq 10\text{mA}$			2	V
$V_{C1H}$	Input Voltage	$V_{C10} = (\text{HIGH});  I_{C1}  \leq 10\text{mA}$	2.8			V
		$V_{C20} = (\text{HIGH});  I_{C2}  \leq 10\text{mA}$	2.8			V
		$V_{C30} = (\text{HIGH});  I_{C3}  \leq 10\text{mA}$	2.8			V
$V_{C1h}$	Input Threshold Level Hysteresis		0.08	0.2	0.4	V
			0.08	0.2	0.4	V
			0.08	0.2	0.4	V
$ I_{C1L} $ $ I_{C2L} $ $ I_{C3L} $	Input Currents	$0 \leq V_{C1l}, V_{C2l}, V_{C3l} \leq V_z - 0.5V$ $V_z \leq 16V$			400	nA
		$0 \leq V_{C1l}, V_{C2l}, V_{C3l} \leq V_z; V_z \leq 16V$			5	μA
$V_{C1}$ $V_{C2}$ $V_{C3}$	Input Voltage During Clamp	$ I_{C1, 2, 3}  = 10\text{mA}$			30	V
		$ I_{C1, 2, 3}  = -10\text{mA}$	-1.5			V
$V_{C10L}$	Output Saturation Voltage	$V_{C10} = (\text{LOW});  I_{C10}  \leq 3\text{mA}$			0.4	V
		$V_{C20} = (\text{LOW});  I_{C20}  \leq 3\text{mA}$			0.4	V
		$V_{C30} = (\text{LOW});  I_{C30}  \leq 3\text{mA}$			0.4	V
$I_{C10L}$ $I_{C20L}$ $I_{C30L}$	Output Short Circuit	$V_{C10} = V_{C20} = V_{C30} = 6V$ ; no damage		10		mA
				10		mA
				10		mA

## ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V <sub>C10H</sub>	Output Voltage High State	10MΩ ≤ R <sub>LC10</sub>	V <sub>ST</sub> -0.25	V <sub>ST</sub> -0.1	V <sub>ST</sub>	V
V <sub>C20H</sub>		10MΩ ≤ R <sub>LC20</sub>	V <sub>ST</sub> -0.25	V <sub>ST</sub> -0.1	V <sub>ST</sub>	V
V <sub>C30H</sub>		10MΩ ≤ R <sub>LC30</sub>	V <sub>ST</sub> -0.25	V <sub>ST</sub> -0.1	V <sub>ST</sub>	V
R <sub>A</sub>	Comparator Output Pull-Up Resistor	Output Status = (HIGH); -0.3 ≤ V <sub>C10</sub> , V <sub>C20</sub> , V <sub>C30</sub> ≤ 25V	7	10	18	KΩ
f <sub>TC1, 2, 3</sub>	Transmission Frequency	C <sub>L1</sub> , C <sub>L2</sub> , C <sub>L3</sub> ≤ 20pF (external load capacitors)	200			KHz
t <sub>1C1, 2, 3</sub>	Off Delay Time	V <sub>C11</sub> , V <sub>C21</sub> , V <sub>C31</sub> = -1 to 16V			1.5	μs
t <sub>2C1, 2, 3</sub>	On Delay Time	I <sub>C1, 2, 3</sub>   ≤ 10mA for the definition of t <sub>1</sub> , t <sub>2</sub> see fig.1			1.0	μs
Δt <sub>1-2</sub>	On Off Delay Time Difference	t <sub>1C</sub> , t <sub>2C</sub>   <sub>1,2,3</sub>			1.0	μs
I <sub>P1DC</sub> I <sub>P2DC</sub>	DC Input Currents	V <sub>P1</sub> = 0; V <sub>P2</sub> = 0			10	μs
		V <sub>P1, P2</sub> = V <sub>ST</sub>			25	μA
		50mV ≤ V <sub>P1</sub> ≤ V <sub>ST</sub> -50mV 50mV ≤ V <sub>P2</sub> ≤ V <sub>ST</sub> -50mV			5	μA
		500mV ≤ V <sub>P1</sub> ≤ V <sub>ST</sub> -500mV 500mV ≤ V <sub>P2</sub> ≤ V <sub>ST</sub> -500mV			2	μA
V <sub>P1DC</sub> V <sub>P2DC</sub>		I <sub>P1, 2</sub> = 10mA			V <sub>ST</sub> +200	V
		I <sub>C1, 2</sub> = -10mA	-200			mV
V <sub>P1TR</sub> V <sub>P2TR</sub>	Dynamic overshoot (with respect to 0 or V <sub>ST</sub> )	Input pulse specific. R <sub>i</sub> = 10KΩ; V <sub>P1</sub> = ±100V; t <sub>r</sub> = 10ns; t <sub>f</sub> = 100ns; within a max. overshoot time t <sub>o</sub> ≤ 20ns, higher overshoot value is possible. *1	-300		300	mV
V <sub>KIL</sub>	Input Voltage Low State	Output Status Low 4.75V ≤ V <sub>Diag</sub> ≤ 5.25V <sup>1)</sup>			2.0	V
		6V ≤ V <sub>Diag</sub> ≤ 20V <sup>2)</sup>  I <sub>KI</sub>   ≤ 10mA			0.4V <sub>Diag</sub>	V
		Output Status Low 20V ≤ V <sub>Diag</sub>  I <sub>KI</sub>   ≤ 10mA			8	V
V <sub>KIH</sub>	Input Voltage High State	Output Status High 4.75V ≤ V <sub>Diag</sub> ≤ 5.25V <sup>1)</sup>	2.9			V
		6V ≤ V <sub>Diag</sub> ≤ 20V <sup>2)</sup>  I <sub>KI</sub>   ≤ 10mA	0.6V <sub>Diag</sub>			V
		Output Status High 20V ≤ V <sub>Diag</sub> <sup>2)</sup>  I <sub>KI</sub>   ≤ 10mA	12			V
V <sub>Klh</sub>	Input Threshold Hysteresis		0.08	0.2	0.4	V
V <sub>KICL</sub>	Input Voltage During Clamp	I <sub>KICL</sub> = 10mA	50			V
		I <sub>KICL</sub> = -10mA	-1.5			V
I <sub>KI</sub>	Input Current	0 ≤ V <sub>KI</sub> ≤ 16V			3	μA
R <sub>KI</sub>	Equivalent Input Resistor 6V ≤ V <sub>KL</sub> ≤ 16V	GND ≤ V <sub>Z</sub> ≤ V <sub>KI</sub> ; 6V ≤ V <sub>Z</sub> ≤ 16V	200			KΩ
		V <sub>Z</sub> = GND	50			KΩ
		V <sub>Z</sub> = open	50			KΩ

\* 1 Guaranteed by design. Not feasible to check on ATE.

1) according to SDL specification

2) according to ISO specification

## ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$V_{LIL}$	Input Voltage Low State	Output Status = LOW; $ I_{L1}  \leq 10\text{mA}$ ; $6V \leq V_Z \leq 16V$			0.4V $Z$	V
		Output Status = LOW; $ I_{L1}  \leq 10\text{mA}$ ; $20V \leq V_Z$			8	V
$V_{LIH}$	Input Voltage High State	Output Status = HIGH; $ I_{L1}  \leq 10\text{mA}$ ; $6V \leq V_Z \leq 20V$	0.6V $Z$			V
		Output Status = HIGH; $ I_{L1}  \leq 10\text{mA}$ ; $20V \leq V_Z$	12			V
$V_{Lih}$	Input Threshold hysteresis		0.08	0.2	0.4	V
$ I_{LI} $	Input Current	$0V \leq V_L \leq 16V$			3	$\mu A$
$V_{LI}$	Input Voltage During Clamp	$I_{LI} = 10\text{mA}$			30	V
		$I_{LI} = -10\text{mA}$	-1.5			V
$R_{LI}$	Equivalent Input Resistor $6V \leq V_L \leq 16V$	$GND \leq V_Z \leq V_{LI}$ ; $6V \leq V_Z \leq 16V$	200			$K\Omega$
		$V_Z = GND$	50			$K\Omega$
		$V_Z = OPEN$	50			$K\Omega$
$V_{TXL}$	Input Voltage Low State		-0.15		1	V
$V_{TXH}$	Input Voltage High State		2		$V_{ST}-0.15$	V
$R_E$	Input Resistors at TX	$0.15V \leq V_{TX} \leq V_{ST}+0.15V$	14	20	36	$K\Omega$
$V_{RXL}$ $V_{LOL}$	Output Saturation Voltage	$V_{LI}, V_{KI} = (\text{LOW})$ $I_{RX}, I_{LO} = 3\text{mA}$			0.4	V
$I_{RX}$ $I_{LO}$	Output Short Circuit Current	$V_{RX}, V_{LO} = 6V$ no damage		10		mA
$V_{RXH}$ $V_{LOH}$	Output Voltage High State	$10M\Omega \leq R_{LRX}; 10M\Omega \leq R_{LLO}$	$V_{ST}-0.25$	$V_{ST}-0.1$	$V_{ST}$	V
$R_A$	Output Pull-up Resistor LO Output	Output Status (HIGH) $-0.3V \leq V_{LO} \leq 25V$	7	10	18	$K\Omega$
		$ I_{KO}  = 10\text{mA}$			0.3	V
		$ I_{KO}  = 30\text{mA} @ V_{Diag} = V_Z$ $ I_{KO}  = 20\text{mA} @ V_{Diag} = V_{ST}$			0.5	V
$I_{Kosc}$	Output Short Circuit Current	$V_{KO} = 16V$ no damage		50		mA
$ I_{KOH} $	Output Leakage Current	Output K = (HIGH) $20V < V_{KO} \leq 50V$ (for output K voltage $20V < V_{KO} \leq 50V$ the output may be disabled internally) $0V \leq V_Z \leq 40V; 0V \leq V_{ST} \leq 6V$			50	$\mu A$
$R_{KOH}$	D.C. Static Output OFF impedance	$0V \leq V_{KO} \leq 20V$ $0V \leq V_Z \leq 40V$ $0V \leq V_{ST} \leq 6V$	200			$K\Omega$
$ I_{RXH} $	Output Leakage Current	Output RX = (HIGH) $0 \leq V_{RX} \leq V_{ST}$			10	$\mu A$
$f_{LI\_LO}$ $f_{KL\_RX}$ $f_{TX\_KO}$	Transmission Frequency	$C_{LO}, C_{RX}, C_{KO} \leq 15\text{pF}$ (external loads)	200			KHz
		$R_{RX} = 10K\Omega$ to $V_{ST}$	200			KHz
		$R_{KO} \leq 1.5K\Omega$ to $V_{Diag} = V_Z$	10	60		KHz
		$R \leq 910\Omega$ to $V_{Diag} = V_{ST}$ ; $C_{KOiso} \leq 1.3\text{nF}$	5	12		KHz
$C_{KOi}$	Internal Output Capacity				20	pF

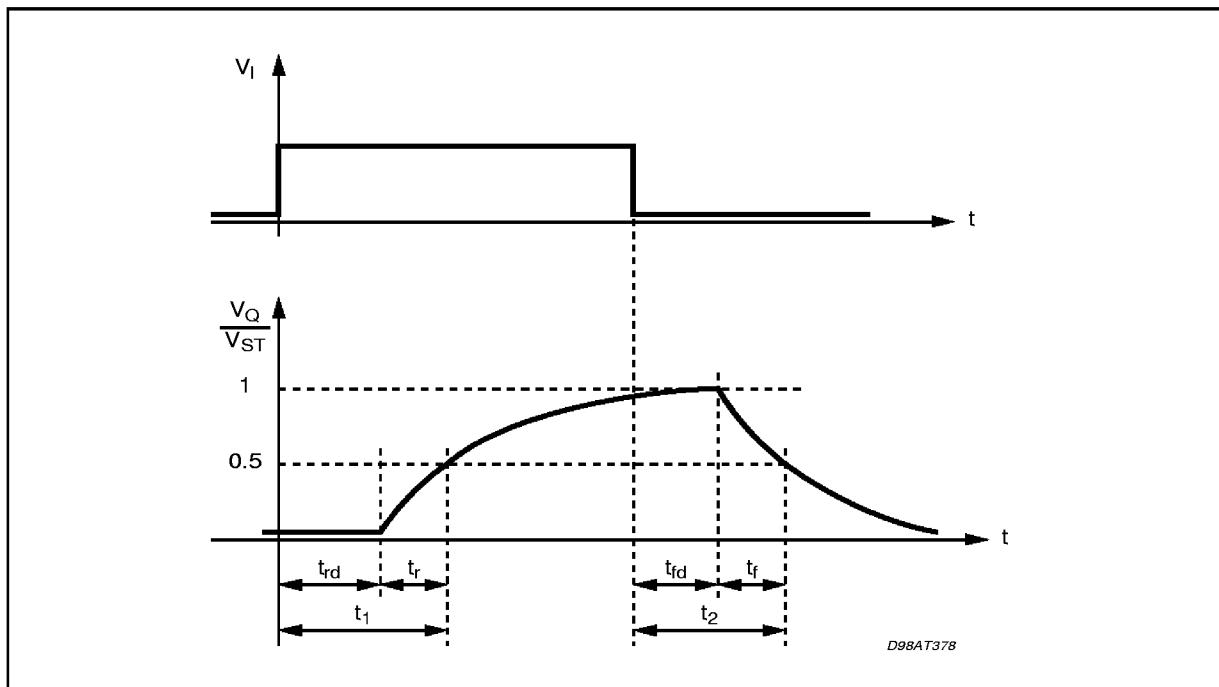
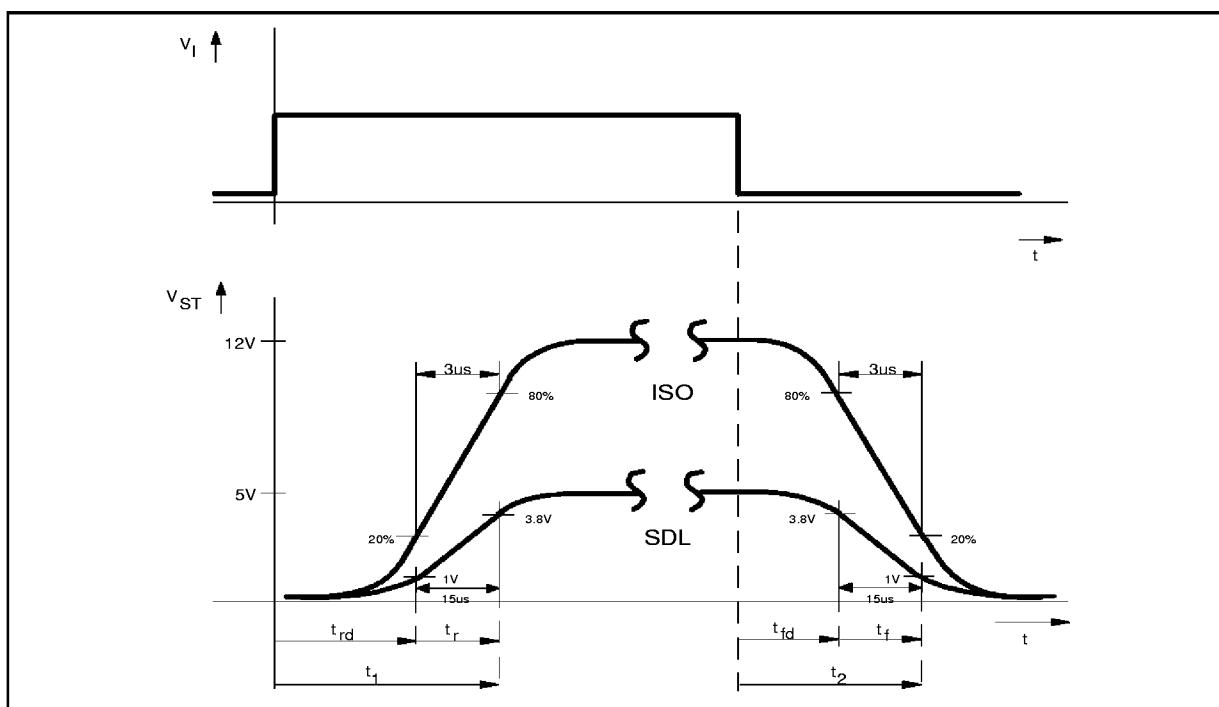
**ELECTRICAL CHARACTERISTICS (continued)**

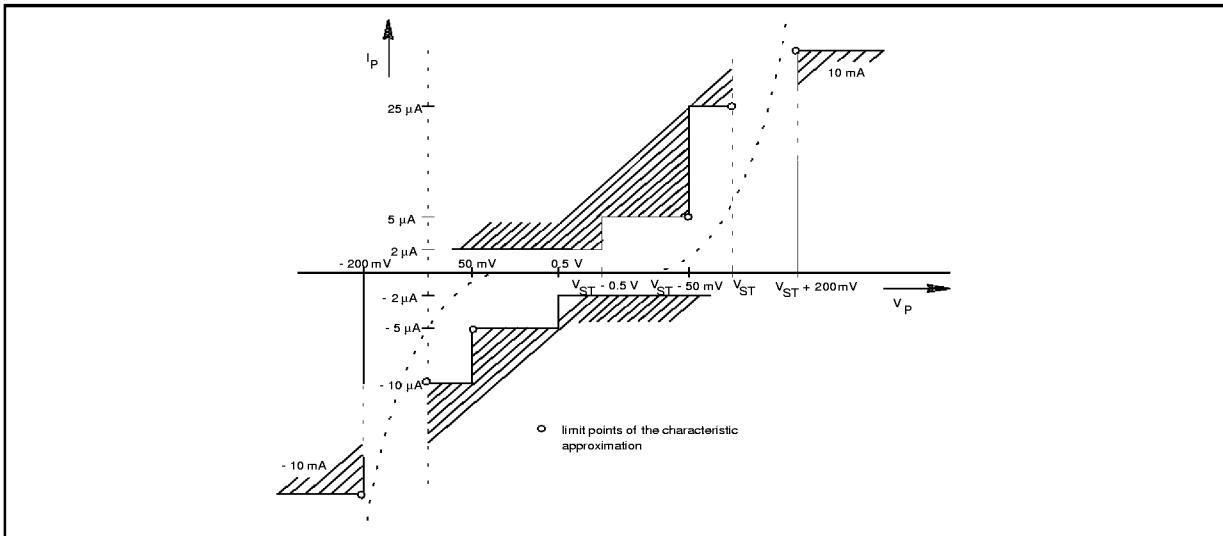
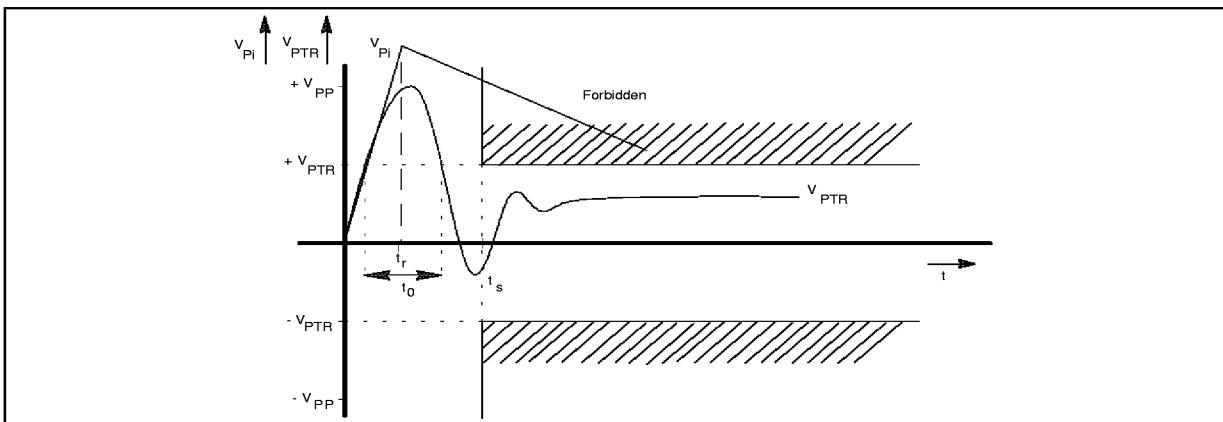
<b>Symbol</b>	<b>Parameter</b>	<b>Test Condition</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
t <sub>1,LI-LO</sub> t <sub>1,KI-RX</sub> t <sub>r,TX-KO/SDL</sub> t <sub>r,TX-KO/ISO</sub>	Rise Time	for the definition of t <sub>1</sub> , t <sub>2</sub> see fig 2 for SDL: V <sub>Diag</sub> = V <sub>ST</sub> = 5V V <sub>Z</sub> = 12V T <sub>j</sub> 25°C, (1)  for ISO: V <sub>Diag</sub> = V <sub>Z</sub> = 12V	10	1.5 1.5 3	20 5.0	μs μs μs μs
t <sub>2,LI-LO</sub> t <sub>2,KI-RX</sub> t <sub>r,TX-KO/SDL</sub> t <sub>r,TX-KO/ISO</sub>	Fall Time			1.5 1.5 3	20 5.0	μs μs μs μs
V <sub>ext KO</sub>	External KO Negative Clamp Voltage	R <sub>LKO</sub> = 75Ω; V <sub>KO</sub> ≥ V <sub>KO</sub> sub-diode @ I <sub>KO</sub> = -100μA, V <sub>Z</sub> = 0V; T <sub>j</sub> = 25°C	-1.5			V
<b>Inverter Matrix / Static Input Signal</b>						
V <sub>IN1,2L</sub>	Input Voltage Low		-0.15		1	V
V <sub>IN1,2H</sub>	Input Voltage High		2		V <sub>ST</sub> +0.15	V
R <sub>IN1,2</sub>	Input Resistor at IN1, IN2 Input	-0.15 ≤ V <sub>IN1,2</sub> ≤ V <sub>ST</sub> +0.15V	14	20	36	KΩ
<b>Current Consumption</b>						
I <sub>ST</sub>	Supply Current	V <sub>ST</sub> ≤ 5.25V; C <sub>11,2,3,Tx</sub> , K <sub>I</sub> = (LOW) IN1, IN2 = (LOW) 0V ≤ V <sub>P1,2</sub> ≤ V <sub>ST</sub>			6	mA
I <sub>Z</sub>	Supply Current	V <sub>Z</sub> ≤ 16V			10	mA
I <sub>Diag</sub>	Supply Current	4.75V ≤ V <sub>Diag</sub> ≤ 16V			4	mA
V <sub>CCR</sub>	Reverse Supply	R <sub>ext</sub> ≤ 10MΩ @ V <sub>CC</sub> all inputs open V <sub>Z</sub> = V <sub>Diag</sub> = 4.3V			0.2	V
<b>Diode (only on chip available)</b>						
V <sub>CL</sub>	Clamping Voltage	I <sub>F</sub> = 10mA, T <sub>j</sub> = 25°C			1.0	V
T <sub>K</sub>	Clamping Voltage Temp. Coefficient		-25		-1.0	mV/K
V <sub>BR</sub>	Reverse Breakdown Voltage	I <sub>R</sub> = 100μA; T <sub>j</sub> = 125°C	50			V
V <sub>BRSUB</sub>	Substrate Breakdown Voltage	I <sub>Sub</sub> = 100μA; T <sub>j</sub> = 125°C	50			V

1) According to GM Serial specification XDE-5024 a line disturbance lower than 20μV for any frequencies higher than 530kHz is realized by means of controlling the leading and the falling edge and by shaping the transition points of the trapezoidal waveform of the output signal.

**Control Function Truth Table**

<b>IN1</b>	<b>IN2</b>	<b>DIAGNOSTIC STATUS</b>	
L	L	RX = $\overline{KI}$	KO = $\overline{TX}$
L	H	RX = $\overline{KI}$	KO = TX
H	L	RX = KI	KO = $\overline{TX}$
H	H	RX = KI	KO = TX

**Figure 1. Transient Characteristic Comparators****Figure 2.**

**DC Input Characteristics****Dynamic Input Characteristics****FUNCTIONAL DESCRIPTION**

The thermal shut down function switches OFF the K output if the chip temperature increases above the thermal shut down threshold.

If the voltage applied to the KO output will be higher than the K disable threshold the output KO will be switched OFF.

To program the ISO or SDL mode the pin  $V_{Diag}$  must be connected to  $V_z$  or  $V_{ST}$ .

**APPLICATION NOTES**

Because of stability the external network as shown in the application circuit diagram at the protection pins P1, P2 is recommended.

The stray capacitor  $C_{Pi}$  should be kept as small as possible ( $C_{Pi} \leq 5 \text{ pF}$ ).

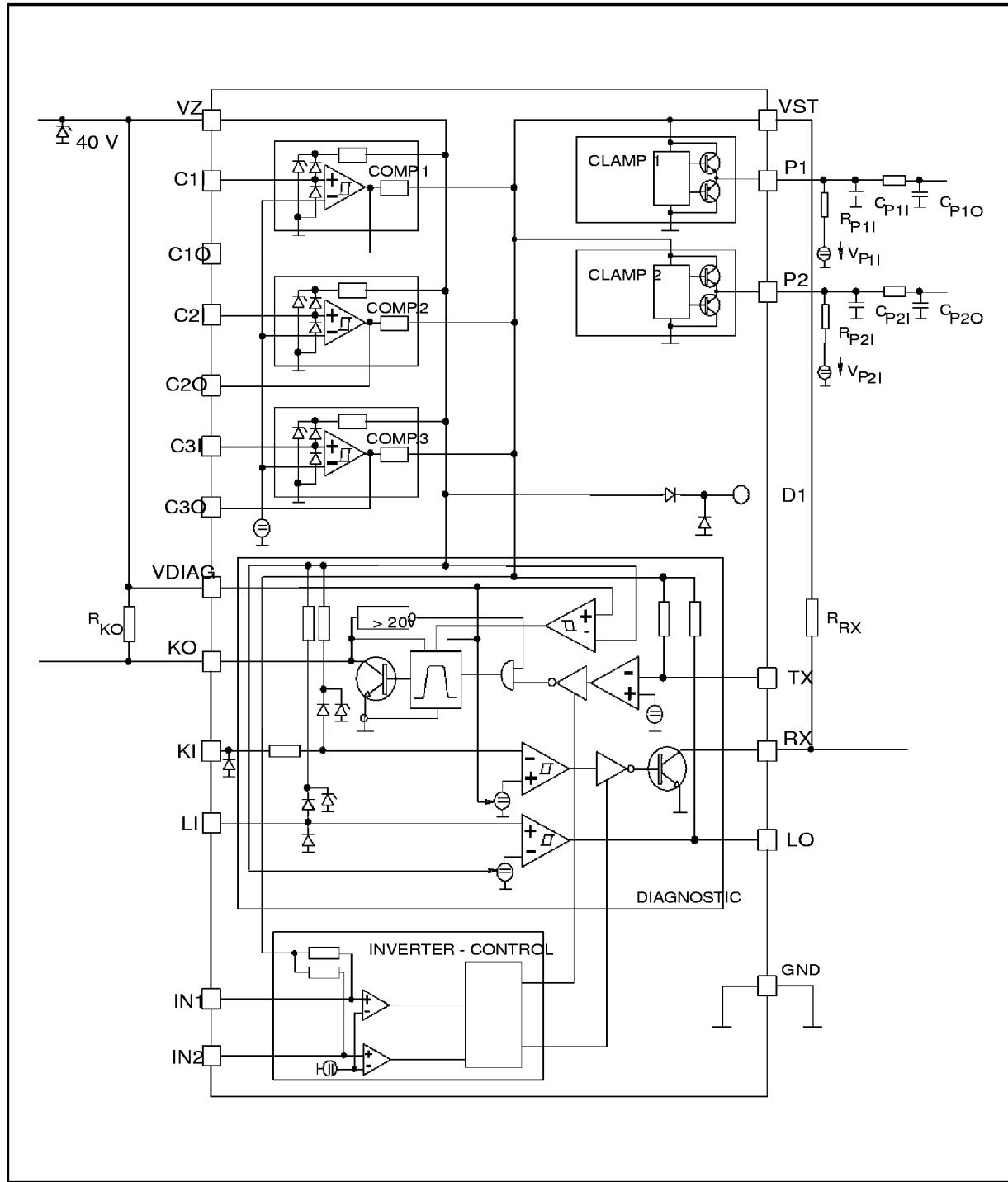
The input current must be limited via the resistor  $R_{Pi}$ . For 10 mA input current is calculated to :

$$R_{Pi} = \frac{V_{Pi,\max}}{10 \text{ mA}}$$

The low pass filter  $R_{Po}$ ,  $C_{Po}$  reduces low voltage high frequency interference during the non clamping range and avoids any oscillation for high voltage spikes.

Recommended values ( $R_{Po} = 10 \text{ k}\Omega$ ,  $C_{Po} = 0.1 \text{ nF}$  ...  $1 \text{ nF}$ ).

## ISO and SDL Application Circuit



## SO20 PACKAGE MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			2.65			0.104
a1	0.1		0.3	0.004		0.012
a2			2.45			0.096
b	0.35		0.49	0.014		0.019
b1	0.23		0.32	0.009		0.013
C		0.5			0.020	
c1			45° (typ.)			
D	12.6		13.0	0.496		0.512
E	10		10.65	0.394		0.419
e		1.27			0.050	
e3		11.43			0.450	
F	7.4		7.6	0.291		0.299
L	0.5		1.27	0.020		0.050
M			0.75			0.030
S			8° (max.)			

